

IN THE CLAIMS:

Claims 13-35 and 41-44 were previously cancelled. Claims 4 and 51 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A method of fabricating an integrated circuit package comprising:
providing a semiconductor die having a plurality of bond pads on an active surface thereof;
providing a lead frame including a plurality of discretely defined conductive leads;
electrically coupling a first bond pad of the plurality of bond pads to a first portion of a first
discretely defined conductive lead of the plurality of conductive leads;
electrically coupling a second bond pad of the plurality of bond pads to a second portion of the
first discretely defined conductive lead; and
electrically isolating the first portion of the first discretely defined conductive lead from the
second portion of the first discretely defined conductive lead.
2. (Original) The method of claim 1, further comprising encapsulating the
semiconductor die and at least a portion of the lead frame in a dielectric material.
3. (Original) The method of claim 2, wherein the electrically isolating the first
portion from the second portion is effected subsequent to the encapsulating.
4. (Currently amended) The method of claim 1, wherein the electrically isolating the
first portion from the second portion of the first discretely defined conductive lead includes
mechanically severing the at least one conductive lead between the first portion and the second
portion.

5. (Previously presented) The method of claim 1, wherein the electrically isolating the first portion from the second portion of the first discretely defined conductive lead includes etching to sever the at least one conductive lead between the first portion and the second portion.

6. (Previously presented) The method of claim 1, wherein the electrically coupling the first bond pad to a first portion of the first discretely defined conductive lead includes wire bonding.

7. (Previously presented) The method of claim 6, wherein the electrically coupling the second bond pad to the second portion of the first discretely defined conductive lead includes wire bonding.

8. (Previously presented) The method of claim 1, further comprising forming a notched region in a surface of the first discretely defined conductive lead between the first portion and the second portion.

9. (Previously presented) The method of claim 8, further comprising encapsulating the semiconductor die and at least a portion of the lead frame including the notched region of the first discretely defined conductive lead in a dielectric material.

10. (Original) The method of claim 9, wherein the electrically isolating the first portion from the second portion includes separating the first portion from the second portion while leaving at least some dielectric material in the notched region.

11. (Previously presented) The method of claim 10, wherein the separating the first portion from the second portion includes cutting the first discretely defined conductive lead into the notched region from an opposing surface of the at least one conductive lead.

12. (Previously presented) A method of forming an array of electrically conductive elements on an integrated circuit package, the method comprising:
securing a semiconductor die having a plurality of bond pads on an active surface thereof to a lead frame having a plurality of discretely defined leads;
electrically coupling at least two spaced locations of each discretely defined lead of the plurality of discretely defined leads with at least two different bond pads of the plurality of bond pads; and
severing each lead between the at least two spaced locations to form at least two electrically isolated conductive elements.

13.-35. (Cancelled)

36. (Previously presented) A method of fabricating a semiconductor die assembly, comprising:
placing a semiconductor die within a plurality of discretely defined leads extending laterally outwardly from peripheral edges thereof;
wire bonding at least two bond pads of a plurality of bond pads on the semiconductor die to at least two spaced locations on each of the discretely defined leads of the plurality;
transfer molding a dielectric encapsulant over the semiconductor die, wire bonds and the plurality of discretely defined leads, leaving undersurfaces of the plurality of discretely defined leads exposed; and
severing each of the plurality of discretely defined leads between each of the at least two spaced locations.

37. (Previously presented) The method of claim 36, further comprising notching upper surfaces of the leads between the at least two spaced locations before the placing the semiconductor die within the plurality of discretely defined leads.

38. (Previously presented) The method of claim 36, wherein the placing the semiconductor die includes securing the semiconductor die to a die paddle located within the plurality of discretely defined leads.

39. (Previously presented) The method of claim 36, wherein the severing is effected by making a linear cut between the spaced locations on each discretely defined lead extending from a common peripheral edge.

40. (Previously presented) The method of claim 39, further comprising notching upper surfaces of the leads between the at least two spaced locations before the placing the semiconductor die within the plurality of leads, and wherein the linear cut is extended substantially only to a depth sufficient to intersect bottoms of the notches so that some dielectric encapsulant remains between the at least two spaced locations.

41.-44. (Cancelled)

45. (Previously presented) The method according to claim 1, wherein providing a lead frame including a plurality of discretely defined conductive leads further includes providing the lead frame with a die paddle and arranging each of the plurality of discretely defined conductive leads so as to extend away from an adjacent peripheral edge of the die paddle at an acute angle relative thereto.

46. (Previously presented) The method according to claim 12, wherein securing a semiconductor die to a leadframe further includes providing the lead frame with a die paddle and arranging each of the plurality of discretely defined conductive leads so as to extend away from an adjacent peripheral edge of the die paddle at an acute angle relative thereto.

47. (Previously presented) The method according to claim 36, wherein placing a semiconductor die within a plurality of discretely defined leads further includes providing a lead frame having a die paddle and arranging each of the plurality of discretely defined conductive leads so as to extend away from an adjacent peripheral edge of the semiconductor die at an acute angle relative thereto.

48. (Previously presented) The method according to claim 37, wherein notching upper surfaces of the leads further comprises defining a concavity within each of the plurality of discretely defined leads exhibiting a width taken in a direction extending between the spaced locations of a first distance and wherein severing each of the plurality of leads between the spaced locations further includes separating the spaced locations by a second distance less than the first distance.

49. (Previously presented) The method of claim 1, wherein electrically isolating the first portion of the first discretely defined conductive lead from the second portion of the first discretely defined conductive lead includes defining a concavity therebetween, and wherein the method further comprises forming a structural member in the concavity including filling the concavity with a volume of electrically insulating material.

50. (Previously presented) The method of claim 12, wherein severing each lead between the at least two spaced locations to form at least two electrically isolated conductive elements includes defining a concavity therebetween, and wherein the method further comprises forming a structural member in the concavity including filling the concavity with a volume of electrically insulating material.

51. (Currently amended) The method of claim 36, wherein severing each of the plurality of discretely defined leads between each of the at least two spaced locations includes defining a concavity therebetween, and wherein the method further comprises forming a structural member in the concavity including filling the concavity with a volume of electrically insulating material.